2SD1261, 2SD1261A

Silicon NPN triple diffusion planar type darlington

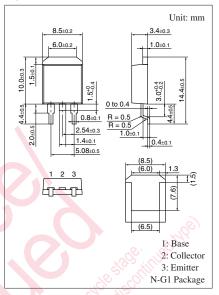
For power amplification Complementary to 2SB0938, 2SB0938A

■ Features

- High forward current transfer ratio hFE
- High-speed switching
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

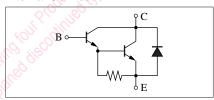
■ Absolute Maximum Ratings $T_C = 25$ °C

| Parameter | Symbol | Rating | Unit | |
|-----------------------------|---------------------|------------------|------|----|
| Collector-base voltage | 2SD1261 | V_{CBO} | 60 | V |
| (Emitter open) | 2SD1261A | | 80 | |
| Collector-emitter voltage | 2SD1261 | V _{CEO} | 60 | V |
| (Base open) | 2SD1261A | | 80 | |
| Emitter-base voltage (Col | V _{EBO} | 5 | V | |
| Collector current | I_{C} | 4 | A | |
| Peak collector current | I_{CP} | 8 | A | |
| Collector power dissipation | P _C | 40 | W | |
| | $T_a = 25^{\circ}C$ | | 1.3 | |
| Junction temperature | | T_{j} | 150 | °C |
| Storage temperature | T_{stg} | -55 to +150 | °C/0 | |



Note) Self-supported type package is also prepared

Internal Connection



\blacksquare Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

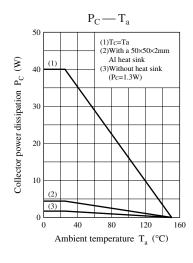
| Parameter | | Symbol | Conditions | Min | Тур | Max | Unit |
|--|----------|----------------------|---|-------|-----|--------|------|
| Collector-emitter voltage | 2SD1261 | V_{CEO} | $I_C = 30 \text{ mA}, I_B = 0$ | 60 | | | V |
| (Base open) | 2SD1261A | | | 80 | | | |
| Base-emitter voltage | | V_{BE} | $V_{CE} = 3 \text{ V}, I_{C} = 3 \text{ A}$ | | | 2.5 | V |
| Collector-base cutoff current | 2SD1261 | I_{CBO} | $V_{CB} = 60 \text{ V}, I_{E} = 0$ | | | 200 | μΑ |
| (Emitter open) | 2SD1261A | | $V_{CB} = 80 \text{ V}, I_{E} = 0$ | | | 200 | |
| Collector-emitter cutoff | 2SD1261 | I_{CEO} | $V_{CE} = 30 \text{ V}, I_{B} = 0$ | | | 500 | μΑ |
| current (Base open) | 2SD1261A | | $V_{CE} = 40 \text{ V}, I_{B} = 0$ | | | 500 | |
| Emitter-base cutoff current (Collector open) | | I_{EBO} | $V_{EB} = 5 \text{ V}, I_{C} = 0$ | | | 2 | mA |
| Forward current transfer ratio | | $h_{\rm FE1}$ | $V_{CE} = 3 \text{ V}, I_{C} = 0.5 \text{ A}$ | 1 000 | | | _ |
| | | h _{FE2} * | $V_{CE} = 3 \text{ V}, I_{C} = 3 \text{ A}$ | 1 000 | | 10 000 | |
| Collector-emitter saturation voltage | | V _{CE(sat)} | $I_C = 3 \text{ A}, I_B = 12 \text{ mA}$ | | | 2.0 | V |
| | | | $I_C = 5 \text{ A}, I_B = 20 \text{ mA}$ | | | 4.0 | V |
| Transition frequency | | f_T | $V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 1 \text{ MHz}$ | | 20 | | MHz |
| Turn-on time | | t _{on} | $I_C = 3 \text{ A}$ | | 0.5 | | μs |
| Strage time | | t _{stg} | $I_{B1} = 12 \text{ mA}, I_{B2} = -12 \text{ mA}$ | | 4.0 | 8. 16 | μs |
| Fall time | | t_{f} | $V_{CC} = 50 \text{ V}$ | | 1.0 | Olilli | μs |

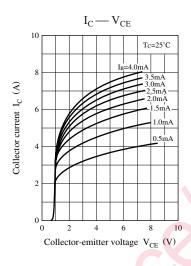
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

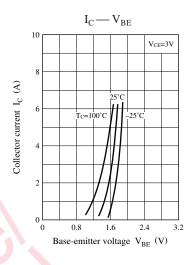
2. *: Rank classification

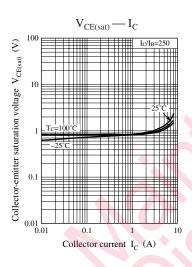
| Rank | R | Q | Р |
|------------------|--------------|--------------|---------------|
| h _{FE2} | 1000 to 2500 | 2000 to 5000 | 4000 to 10000 |

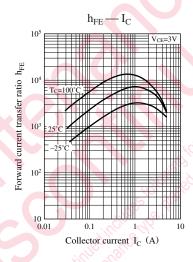
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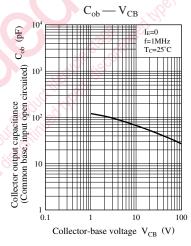


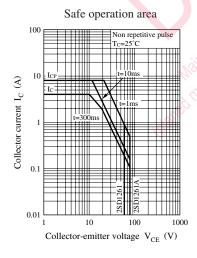


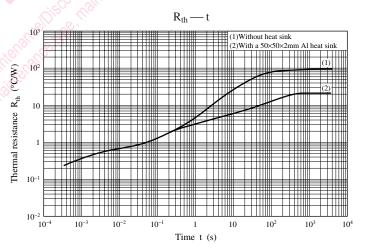












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